Dual N-Channel Power MOSFET

40V, 38A, 15mΩ

FEATURES

- Low $R_{DS(ON)}$ to minimize conductive losses
- Low gate charge for fast power switching
- 100% UIS and R_g tested
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

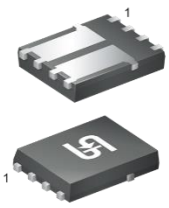
APPLICATIONS

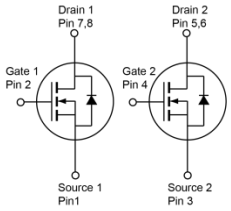
- BLDC Motor Control
- Battery Power Management
- DC-DC Converter
- Secondary Synchronous Rectification

KEY PERFORMANCE PARAMETERS			
PARAMETER		**VALUE**	**UNIT**
V_{DS}		40	V
$R_{DS(on)}$ (max)	V_{GS} = 10V	15	mΩ
	V_{GS} = 7V	28.6	
Q_g		18	nC

Pb-Free RoHS COMPLIANT HALOGEN FREE

PDFN56 Dual





Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)				
PARAMETER		**SYMBOL**	**LIMIT**	**UNIT**
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current (Note 1)	T_C = 25°C	I_D	38	A
	T_A = 25°C		8	
Pulsed Drain Current		I_{DM}	152	A
Single Pulse Avalanche Current (Note 2)		I_{AS}	15	A
Single Pulse Avalanche Energy (Note 2)		E_{AS}	34	mJ
Total Power Dissipation	T_C = 25°C	P_D	40	W
	T_C = 125°C		8	
Total Power Dissipation	T_A = 25°C	P_D	2	W
	T_A = 125°C		0.4	
Operating Junction and Storage Temperature Range		T_J, T_{STG}	- 55 to +150	°C

THERMAL PERFORMANCE			
PARAMETER	**SYMBOL**	**MAXIMUM**	**UNIT**
Junction to Case Thermal Resistance	$R_{\Theta JC}$	3.1	°C/W
Junction to Ambient Thermal Resistance	$R_{\Theta JA}$	61	°C/W

Thermal Performance Note: $R_{\Theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins. $R_{\Theta JC}$ is guaranteed by design while $R_{\Theta CA}$ is determined by the user's board design. The $R_{\Theta JA}$ limit presented here is based on mounting on a 1 in^2 pad of 2 oz copper.

ELECTRICAL SPECIFICATIONS (T_A = 25°C unless otherwise noted)						
PARAMETER	**CONDITIONS**	**SYMBOL**	**MIN**	**TYP**	**MAX**	**UNIT**
Static						
Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250μA	BV_{DSS}	40	--	--	V
Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 250μA	$V_{GS(TH)}$	2	3	4	V
Gate-Source Leakage Current	V_{GS} = ±20V, V_{DS} = 0V	I_{GSS}	--	--	±100	nA
Drain-Source Leakage Current	V_{GS} = 0V, V_{DS} = 40V	I_{DSS}	--	--	1	μA
	V_{GS} = 0V, V_{DS} = 40V T_J = 125°C		--	--	100	
Drain-Source On-State Resistance (Note 3)	V_{GS} = 10V, I_D = 8A	$R_{DS(on)}$	--	11	15	mΩ
	V_{GS} = 7V, I_D = 6A		--	15	28.6	
Forward Transconductance (Note 3)	V_{DS} = 10V, I_D = 8A	g_{fs}	--	32	--	S
Dynamic (Note 4)						
Total Gate Charge	V_{GS} = 10V, V_{DS} = 20V, I_D = 8A	Q_g	--	18	--	nC
Total Gate Charge	V_{GS} = 7V, V_{DS} = 20V, I_D = 6A	Q_g	--	13	--	
Gate-Source Charge		Q_{gs}	--	6	--	
Gate-Drain Charge		Q_{gd}	--	4	--	
Input Capacitance	V_{GS} = 0V, V_{DS} = 20V f = 1.0MHz	C_{iss}	--	1132	--	pF
Output Capacitance		C_{oss}	--	110	--	
Reverse Transfer Capacitance		C_{rss}	--	51	--	
Gate Resistance	f = 1.0MHz	R_g	0.6	2.1	4.2	Ω
Switching (Note 4)						
Turn-On Delay Time	V_{GS} = 10V, V_{DS} = 20V, I_D = 8A, R_G = 2Ω	$t_{d(on)}$	--	6	--	ns
Turn-On Rise Time		t_r	--	7	--	
Turn-Off Delay Time		$t_{d(off)}$	--	12	--	
Turn-Off Fall Time		t_f	--	3	--	
Source-Drain Diode						
Forward Voltage (Note 3)	V_{GS} = 0V, I_S = 8A	V_{SD}	--	--	1.2	V
Reverse Recovery Time	I_S = 8A, dI/dt = 100A/μs	t_{rr}	--	14	--	ns
Reverse Recovery Charge		Q_{rr}	--	7	--	nC

Notes:

1. Silicon limited current only.
2. L = 0.3mH, V_{GS} = 10V, V_{DD} = 25V, R_G = 25Ω, I_{AS} = 15A, Starting T_J = 25°C
3. Pulse test: Pulse Width ≤ 300μs, duty cycle ≤ 2%.
4. Switching time is essentially independent of operating temperature.

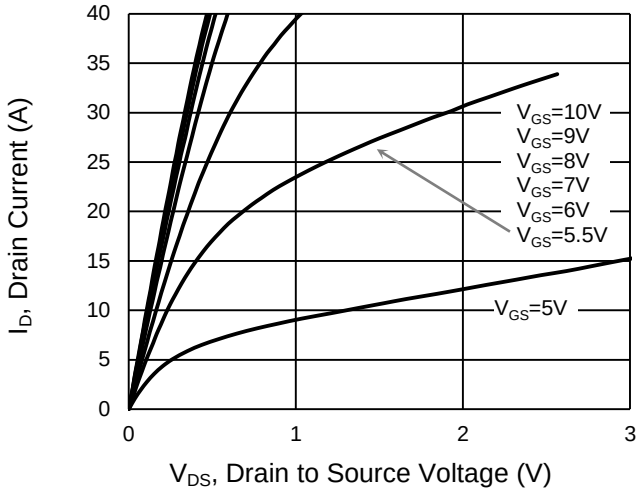
ORDERING INFORMATION

ORDERING CODE	PACKAGE	PACKING
TSM150NB04DCR RLG	PDFN56 Dual	2,500pcs / 13” Reel

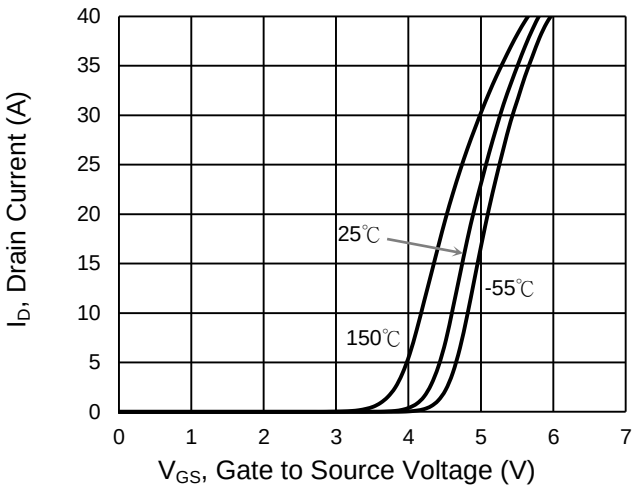
CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

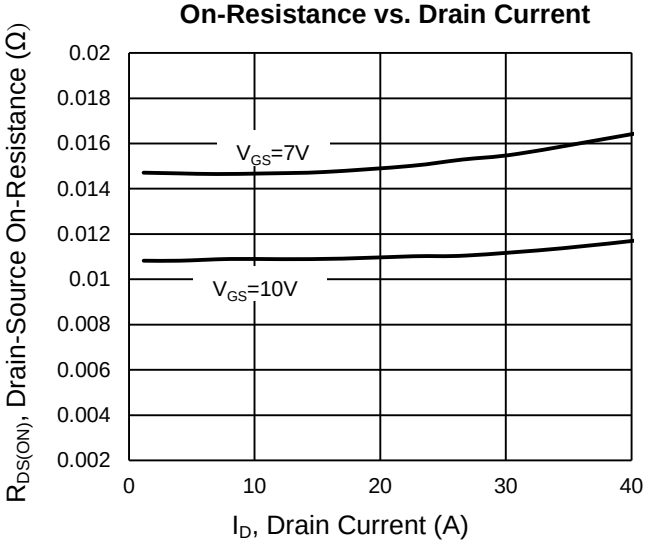
Output Characteristics



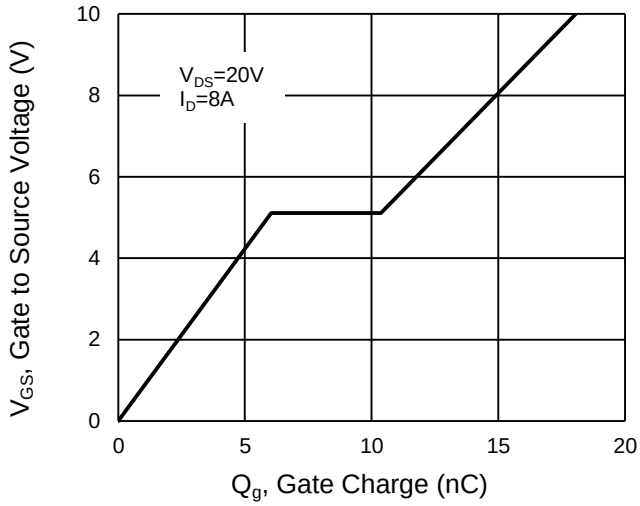
Transfer Characteristics



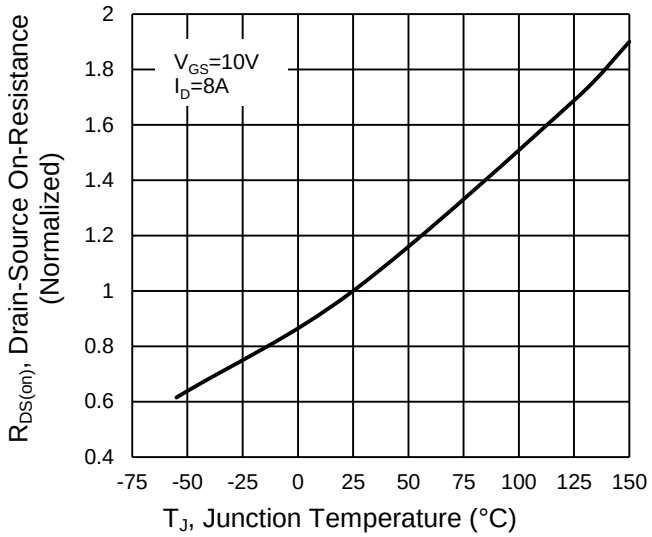
On-Resistance vs. Drain Current



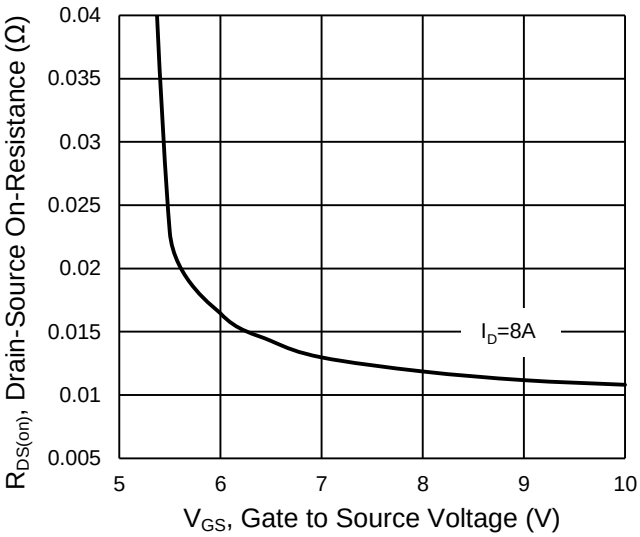
Gate-Source Voltage vs. Gate Charge



On-Resistance vs. Junction Temperature



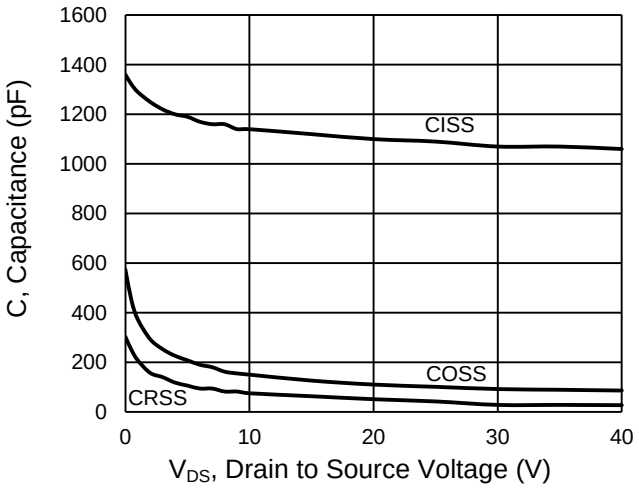
On-Resistance vs. Gate-Source Voltage



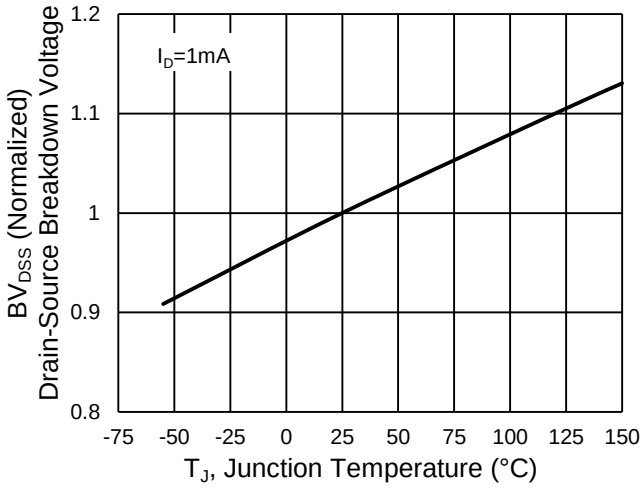
CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

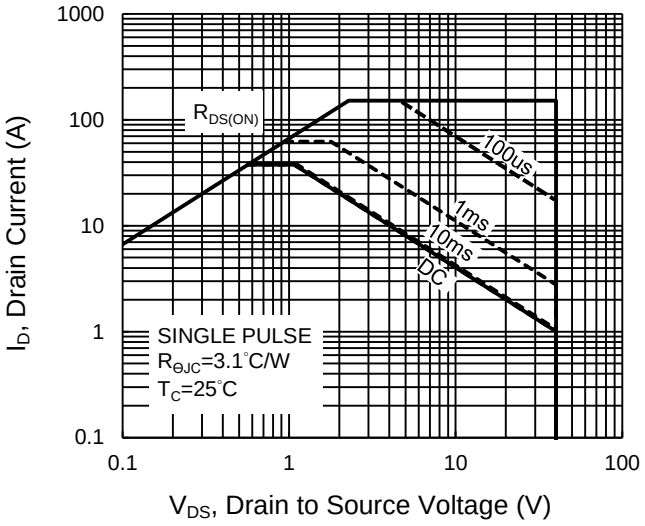
Capacitance vs. Drain-Source Voltage



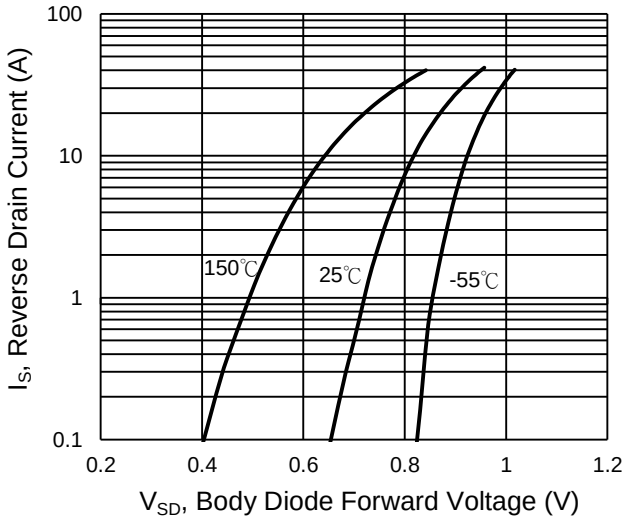
BV_{DSS} vs. Junction Temperature



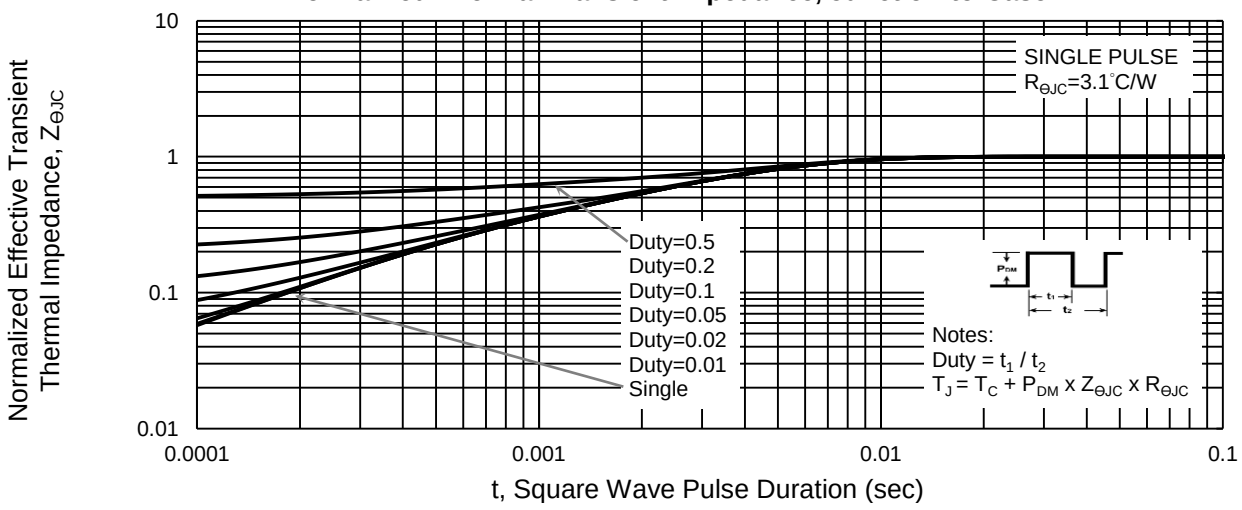
Maximum Safe Operating Area, Junction-to-Case



Source-Drain Diode Forward Current vs. Voltage

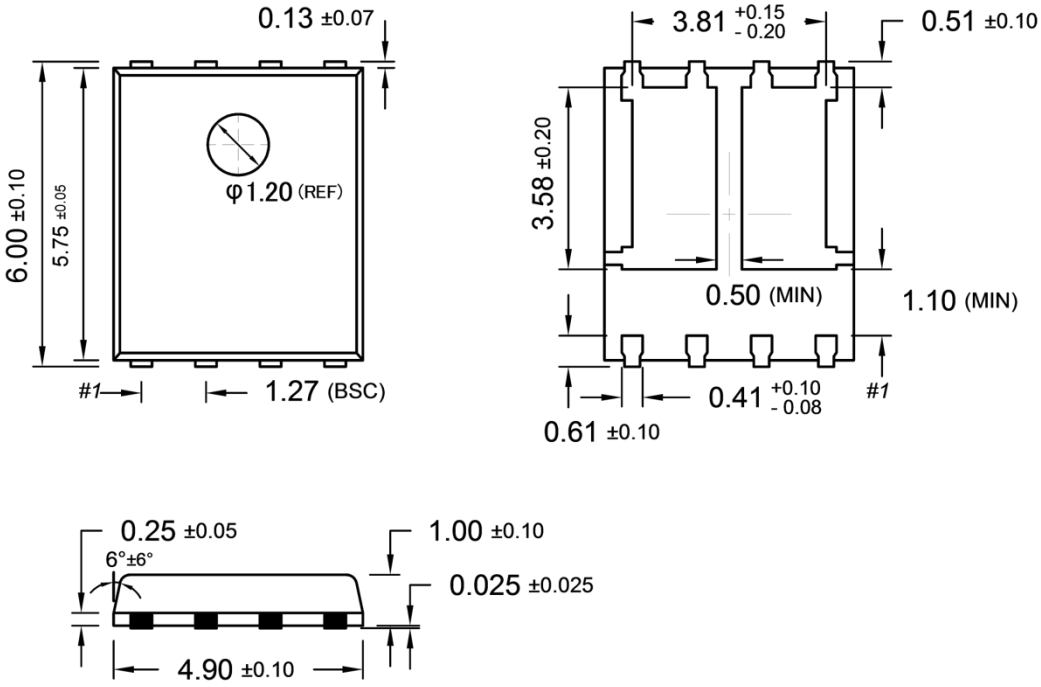


Normalized Thermal Transient Impedance, Junction-to-Case

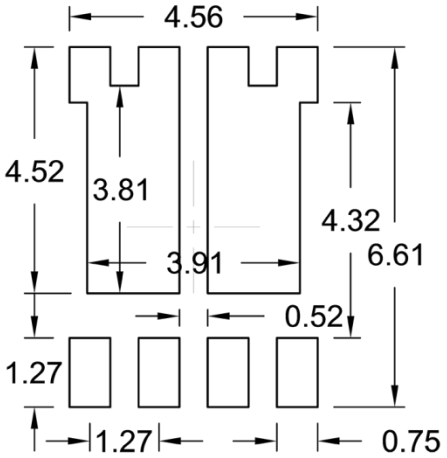


PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

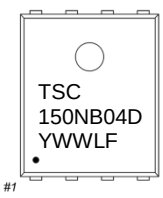
PDFN56 Dual



SUGGESTED PAD LAYOUT (Unit: Millimeters)



MARKING DIAGRAM



Y = Year Code
WW = Week Code (01~52)
L = Lot Code (1~9,A~Z)
F = Factory Code

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.